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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/472,757	12/27/1999	ROBERT J. O'DONNELL	LAM133/P0582	9169
22434	7590 03/27/2003			
BEYER WEAVER & THOMAS LLP			EXAMINER	
	P.O. BOX 778 BERKELEY, CA 94704-0778		UMEZ ERONINI, LYNETTE T	
			ART UNIT	PAPER NUMBER
			1765	15
			DATE MAILED: 03/27/2003	15

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	pplicant(s)	
Advisory Acti n	09/472,757	O DONNELL, ROBE	RT J.
Advisory Acti II	Examin r	Art Unit	
·	Lynette T. Umez-Eronini	1765	
The MAILING DATE of this communication appe	ars on the cover sheet with th	rrespondence addi	ress
THE REPLY FILED 27 February 2003 FAILS TO PLACE Therefore, further action by the applicant is required to av final rejection under 37 CFR 1.113 may only be either: (1) condition for allowance; (2) a timely filed Notice of Appeal Examination (RCE) in compliance with 37 CFR 1.114.	oid abandonment of this applica a timely filed amendment which	ation. A proper reply h places the applicat	to a tion in
PERIOD FOR RE	PLY [check either a) or b)]		
a) The period for reply expiresmonths from the mailing b) The period for reply expires on: (1) the mailing date of this A no event, however, will the statutory period for reply expire to ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS 706.07(f).  Extensions of time may be obtained under 37 CFR 1.136(a). The	dvisory Action, or (2) the date set forth ater than SIX MONTHS from the mailing FILED WITHIN TWO MONTHS OF TH	g date of the final rejection.	on. See MPEP
fee have been filed is the date for purposes of determining the period of fee under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the context (2) as set forth in (b) above, if checked. Any reply received by the Office timely filed, may reduce any earned patent term adjustment. See 37 C.	f extension and the corresponding amo he shortened statutory period for reply the later than three months after the mail	unt of the fee. The appropriate or the final Control of the final Contro	opriate extension Office action; or
1. A Notice of Appeal was filed on Appellant's 37 CFR 1.192(a), or any extension thereof (37 CFR			
2. The proposed amendment(s) will not be entered be	cause:		
(a) X they raise new issues that would require further	er consideration and/or search (s	see NOTE below);	
(b)  they raise the issue of new matter (see Note be	elow);		
(c) they are not deemed to place the application in issues for appeal; and/or	better form for appeal by mate	rially reducing or sim	nplifying the
(d)  they present additional claims without canceling	ng a corresponding number of fi	nally rejected claims	<b>S</b> .
NOTE: See Continuation Sheet.			
3. Applicant's reply has overcome the following rejection	on(s):		
4. Newly proposed or amended claim(s) would canceling the non-allowable claim(s).	be allowable if submitted in a se	eparate, timely filed a	amendment
5. ☐ The a) ☐ affidavit, b) ☐ exhibit, or c) ☐ request for application in condition for allowance because:		dered but does NOT	place the
6. The affidavit or exhibit will NOT be considered becaraised by the Examiner in the final rejection.	ause it is not directed SOLELY to	o issues which were	newly
7. For purposes of Appeal, the proposed amendment( explanation of how the new or amended claims wo			nd an
The status of the claim(s) is (or will be) as follows:			
Claim(s) allowed: none.			
Claim(s) objected to: <u>none</u> .			
Claim(s) rejected: <u>1-15,19 and 20</u> .			
Claim(s) withdrawn from consideration: none.			
8. The proposed drawing correction filed on is a	a)☐ approved or b)☐ disapp	roved by the Examin	ner.
9. Note the attached Information Disclosure Statemen	t(s)( PTO-1449) Paper No(s)	*	
10. Other:			

## Continuation of 2. NOTE:

In (Once Amended) Claim 1, "A method of . . . stripping . . . --most of the-- residual sidewall . . .--wherein plasma created by the etch mask stripping gas strips away the etch mask and removes most of the residual sidewall passivation-- . .;

In (Once Amended) (Claim 15), "A method for . . . --using a stripping gas to strip-- . . . and --remove most of the-- sidewall . . . "; In (Twice Amended) Claim 17, "--An apparatus for performing the-- method, . . . in claim 1"; and In (Once Amended) Claim 19,"--A semiconductor chip formed by the-- method . . . in claim 1," raise new issues that require further consideration.

> porto BENJAMIN L. UTECH SUPERVISORY PATENT EXAMINER

**TECHNOLOGY CENTER 1700**